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## Patent Abstracts of Japan

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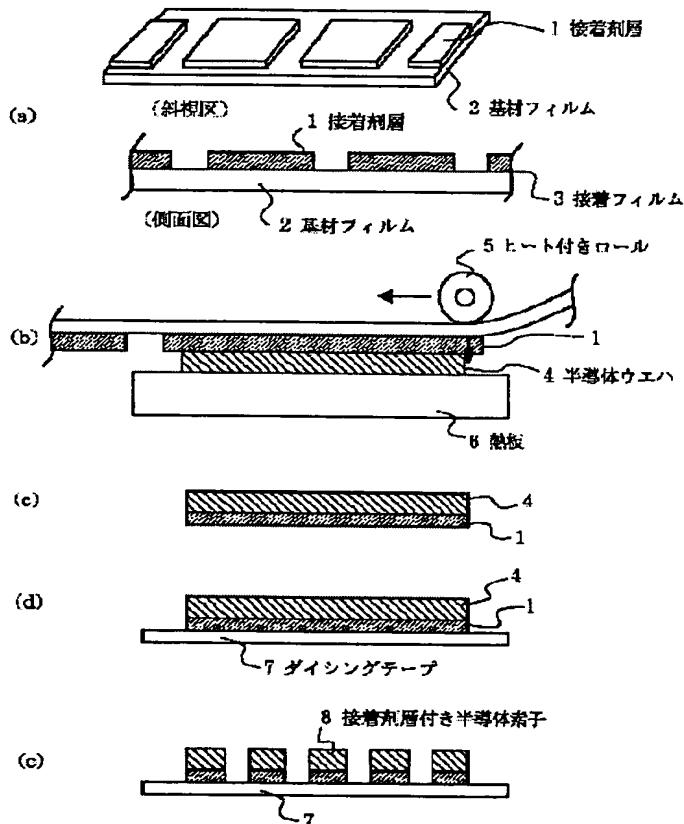
APPLICATION DATE : 27-12-99  
 APPLICATION NUMBER : 11369815

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INT.CL. : H01L 21/52 C09J 7/02

TITLE : METHOD FOR MANUFACTURING  
 ADHESIVE FILM FOR DIE BONDING  
 AND SEMICONDUCTOR DEVICE



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide a method for manufacturing an adhesive film for die bonding, where the loss of film material is small, and there is also no problem of dislocation, and an adhesive layer of equal thickness can be provided, and moreover which can be die-bonded with a simple device and is superior in resistance to solder reflow, and a method of manufacturing a semiconductor device using this.

**SOLUTION:** The adhesive film for die bonding, has a base material film layer and a plurality of adhesive layers having the size of the semiconductor wafers made intermittently on that base material film layer or larger than them and moreover having an oblong pattern form. On the semiconductor wafer rear plane whereupon many semiconductor elements are formed, the adhesive layer of the die bonding adhesive film is bonded by thermocompression, and a wafer having an adhesive layer is obtained. Then after adhering a dicing tape on the adhesive layer plane of such wafer, the wafer is cut into separate semiconductor elements having the adhesive layer. Then, the dicing tape is removed, and the obtained semiconductor element having the adhesive layer is die-bonded to a supporting member.

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